

L Number	Hits	Search Text	DB	Time stamp
1	132	700/99-103,121;702/177,184.ccls. and @pd>=20040714	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 17:17
2	41	(700/99-103,121;702/177,184.ccls. and @pd>=20040714) and maintenance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 17:30
3	25	(700/99-103,121;702/177,184.ccls. and @pd>=20040714) and maintenance and schedul\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 17:35
4	38	maintenance same schedul\$6 same gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 18:08
5	149	(maintenance near schedul\$6) with (downtime or down-time or "down time" or gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 18:09
6	2	(maintenance near schedul\$6) with (gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 18:11
7	17	(maintenance near schedul\$6) with (space or spacing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 18:11
-	204	702/184.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 12:59
-	100	702/177.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:09
-	320	700/100.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:09
-	90	700/100.ccls. and maintenance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:19
-	12	maintenance with schedul\$5 with gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:23
-	564	maintenance near2 gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:24
-	282	maintenance near gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 13:24

-	0	(maintenance near gap) same schedul\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 13:24
-	1	(maintenance near2 gap) same schedul\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 13:24
-	289	maintenance with schedul\$5 with (parallel or downtime or "down time" or "down-time")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 15:29
-	12	maintenance with schedul\$5 with (parallel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 15:32
-	24	maintenance with schedul\$5 with (simultaneous\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 16:00
-	67	(maintenance near (simultaneous\$6 or parallel)) and (downstream or upstream)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 16:08
-	50	maintenance near (downstream or upstream)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 16:09
-	131	maintenance with (downstream or upstream) with (schedul\$5 or perform\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 16:12
-	15175	maintenance near (schedul\$5 or perform\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 16:47
-	4	(maintenance near (schedul\$5 or perform\$5)) with line with (upstream or downstream)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 16:21
-	75	(maintenance near (schedul\$5 or perform\$5)) same ("manufacturing line" or "production line" or "assembly line")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 16:23
-	32	(maintenance near (schedul\$5 or perform\$5)) with downstream	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 17:03
-	401	maintenance near timing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 20:55
-	10	(maintenance near timing) and ("manufacturing line" or "production line" or "assembly line")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/13 20:58

-	2	(maintenance near wait\$5) and ("manufacturing line" or "production line" or "assembly line")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 20:59
-	215	700/121.ccls. and maintenance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 20:59
-	38	700/121.ccls. and (maintenance with schedul\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 21:14
-	13	maintenance with schedul\$9 with idl\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 21:17
-	470	700/99,101-103.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 21:18
-	38	700/99,101-103.ccls. and (schedul\$5 with maintenance)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 21:26
-	30	maintenance with schedul\$9 with during with (downtime or "down time" or "down-time")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 21:42
-	691	ASML-NETHERLANDS-BV ASML-NETHERLANDS-B-V "ASML-NETHERLANDS-B.V" ASML-NETHERLANDS-NV ASML-MASKTOOLS-NETHERLANDS-BV ASML-MASKTOOLS-NETHERLANDS-B-V "ASML-MASKTOOLS-NETHERLANDS-B.V" ASML-MASKTOOLS-B-V "ASML-MASKTOOLS-B.V" ASML-NETHERLANDS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 21:47
-	28	(ASML-NETHERLANDS-BV ASML-NETHERLANDS-B-V "ASML-NETHERLANDS-B.V" ASML-NETHERLANDS-NV ASML-MASKTOOLS-NETHERLANDS-BV ASML-MASKTOOLS-NETHERLANDS-B-V "ASML-MASKTOOLS-NETHERLANDS-B.V" ASML-MASKTOOLS-B-V "ASML-MASKTOOLS-B.V" ASML-NETHERLANDS) and maintenance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 21:53
-	16	maintenance with (coater or developer) with schedul\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 21:55
-	726	(semiconductor or wafer) and ((coater or developer or track) same maintenance)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 21:57
-	35	(semiconductor or wafer) and ((coater or developer or track) same maintenance same schedul\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 22:05
-	556	coater with developer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 22:05

-	5	coater with developer with maintenance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 22:09
-	3	(coater with developer) same maintenance same (expos\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 22:10
-	5	coater same developer same maintenance same (stepper or expos\$5 or photolithography)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/13 22:11
-	324	coater and developer and (stepper or expos\$5 or lithography or photolithography) and maintenance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 12:24
-	3	(coater and developer and (stepper or expos\$5 or lithography or photolithography) and maintenance) and bottleneck	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 12:06
-	39	(coater and developer and (stepper or expos\$5 or lithography or photolithography) and maintenance) and schedul\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 12:07
-	5460	(coater or developer or track) with maintenance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 12:34
-	16	((coater or developer or track) with maintenance with schedul\$5) and (semiconductor or wafer or lithography or photolithography)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 12:26
-	1323	(coater or developer) with maintenance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 12:36
-	161	((coater or developer) with maintenance) and (semiconductor or wafer or photolithography or lithography)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 13:07
-	31	((coater or developer) same maintenance same (schedul\$5 or perform\$5) same (expos\$5 or stepper or photolithography or lithography))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 13:19
-	189	(coater or developer or track) with maintenance with schedul\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:43
-	140	(expos\$5 with longer with (coat\$5 or develop\$)) and maintenance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:45
-	132	700/99-103,121;702/177,184.ccls. and @pd>=20040714	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 17:17